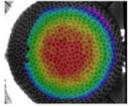
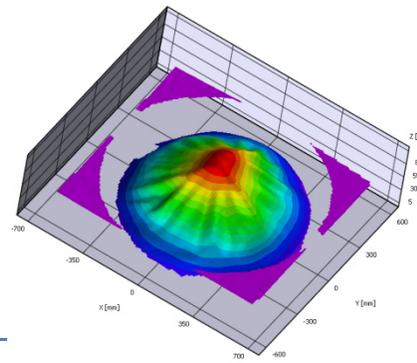


Inter-Laboratory Digital Image Correlation (DIC) Symposium



Goal: The Inter-Lab DIC symposium will provide a forum for researchers working in DIC to share their ideas and collaborate within and between the DOE Labs.

Symposium Dates: June 2-3, 2015 (Please indicate interest in attending or presenting ASAP)

Abstract Due Date: April 15, 2015. Abstracts should be one page including figures. Email to Misti.

Location: Sandia National Laboratories (Albuquerque, NM) with teleconferencing to other DOE labs.

Contact: Misti Cepeda (mcepeda@sandia.gov) (505) 284-6707

Call: Digital Image Correlation (DIC) is a 3D shape, displacement and strain technique that utilizes a myriad of imaging technologies for making quantitative engineering measurements. The flexibility of DIC has made it extremely attractive for determination of material properties and model validation in a broad range of applications.

Topics:

1. DIC Uncertainty Quantification
2. Material characterization
3. Inverse methods, Virtual Fields, etc.
4. High, ultra-high speed DIC
5. Volumetric DIC
6. Future directions of DIC

Suggested Participants:

1. DIC users/developers
2. Material characterization/inverse modeling
3. Model validation/UQ/V&V
4. Interest in full-field measurements

Format: Sessions organized by topic will be concluded with a speaker panel and discussion.

Plenary Speaker: Pascal Lava (KU-Leuven) "Local vs Global DIC for material identification"

Keynote Speakers: Yet to be determined. Probably 3.

Preconference Course: June 1, 8AM – 4PM

Practical aspects of DIC measurements: 2D, Stereo and Volumetric

Phillip Reu will present a *lightning-speed* overview of the practical aspects of DIC measurements. Topics will include: DIC theory, ideal speckling, stereo-DIC and uncertainty quantification. (Subject to having 15 participants.)

Scientific Committee: Phillip Reu (Chair) (plreu@sandia.gov), Dan Turner(dzturne@sandia.gov),
Sharlotte Kramer (slkrame@sandia.gov).

